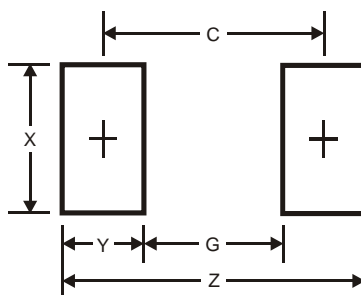
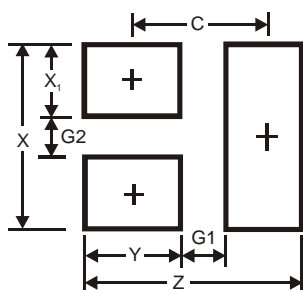


DFN1006-2 / DFN1006H4-2 / MiniMELF / MELF / SOD-323 / SOD-123 / SOD-523 / SMA / SMB / SMC



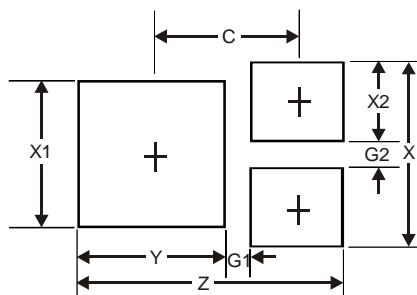
Dimensions	DFN1006-2 / DFN1006H4-2	MiniMELF	MELF	SOD-123	SOD-323	SOD-523	SMA	SMB	SMC
Z	1.1	4.7	6.3	4.9	3.75	2.3	6.5	6.8	9.4
G	0.3	2.1	3.3	2.5	1.05	1.1	1.5	1.8	4.4
X	0.7	1.7	2.7	0.7	0.65	0.8	1.7	2.3	3.3
Y	0.4	1.3	1.5	1.2	1.35	0.6	2.5	2.5	2.5
C	0.7	3.5	4.8	3.7	2.40	1.7	4.0	4.3	6.8

DFN1006-3 / DFN1006H4-3



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
X	0.7
X1	0.25
Y	0.4
C	0.7

DFN1411-3

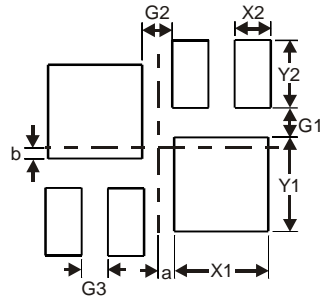


Dimensions	Value (in mm)
Z	1.38
G1	0.15
G2	0.15
X	0.95
X1	0.75
X2	0.40
Y	0.75
C	0.76

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

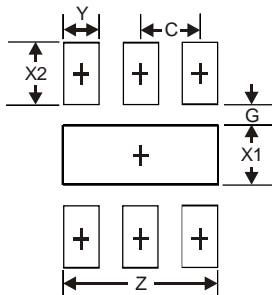
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

DFN1612-6 / DFN1310H4-6



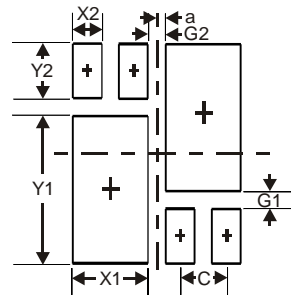
Dimensions	DFN1612-6	DFN1310H4-6
G1	0.15	0.16
G2	0.175	0.17
G3	0.15	0.15
X1	0.60	0.52
X2	0.25	0.20
Y1	0.65	0.52
Y2	0.45	0.375
a	0.10	0.09
b	0.15	0.06

DFN1616-6



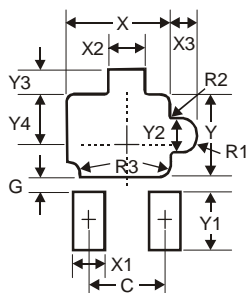
Dimensions	Value (in mm)
Z	1.3
G	0.175
X1	0.50
X2	0.525
Y	0.30
C	0.50

DFN1616-8



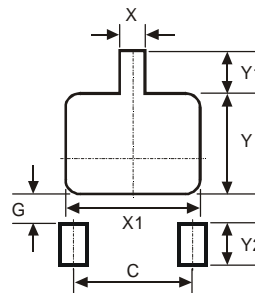
Dimensions	Value (in mm)
G1	0.15
G2	0.20
X1	0.65
X2	0.25
Y1	1.25
Y2	0.50
C	0.40
a	0.10

DFN2020-3



Dimensions	Value (in mm)
C	1.00
G	0.15
X	1.40
X1	0.35
X2	0.45
X3	0.322
Y	1.10
Y1	0.60
Y2	0.45
Y3	0.45
Y4	0.698
R1	0.225
R2	0.05
R3	0.20

DFN2020B-3

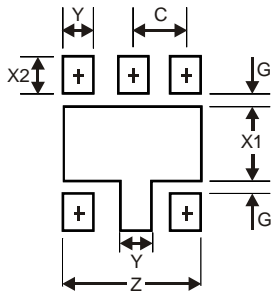


Dimensions	Value (in mm)
C	1.30
G	0.24
X	0.35
X1	1.52
Y	1.09
Y1	0.47
Y2	0.50

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

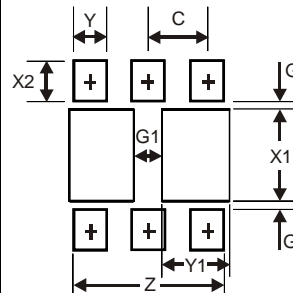
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

DFN2020-6



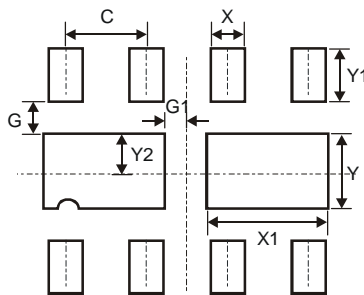
Dimensions	Value (in mm)
Z	1.67
G	0.15
X1	0.90
X2	0.45
Y	0.37
C	0.65

DFN2020B-6



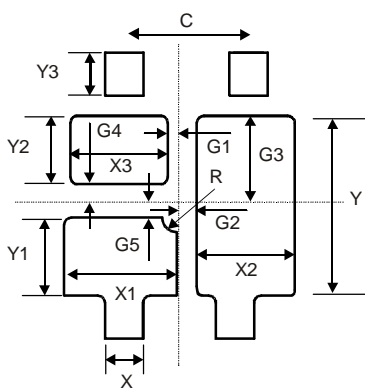
Dimensions	Value (in mm)
Z	1.67
G	0.20
G1	0.40
X1	1.0
X2	0.45
Y	0.37
Y1	0.70
C	0.65

DFN3020B-8



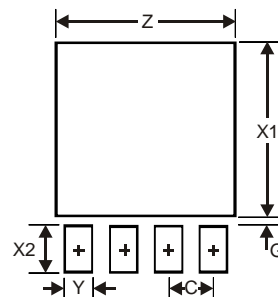
Dimensions	Value (in mm)
C	0.650
G	0.285
G1	0.090
X	0.400
X1	1.120
Y	0.730
Y1	0.500
Y2	0.365

DFN3030-4



Dimensions	Value (in mm)
C	1.300
G1	0.100
G2	0.150
G3	0.830
G4	0.115
G5	0.135
R	0.150
X	0.500
X1	1.375
X2	1.225
X3	1.175
Y	1.980
Y1	1.015
Y2	0.715
Y3	0.650

DFN3030-8

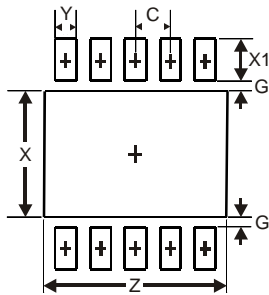


Dimensions	Value (in mm)
Z	2.59
G	0.11
X1	2.49
X2	0.65
Y	0.39
C	0.65

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

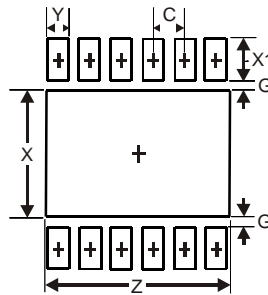
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

DFN3030-10



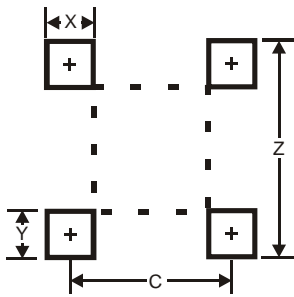
Dimensions	Value (in mm)
Z	2.60
G	0.15
X	1.80
X1	0.60
Y	0.30
C	0.50

DFN3030-12



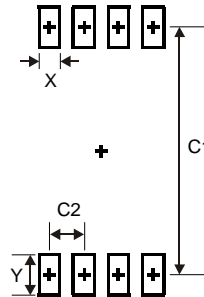
Dimensions	Value (in mm)
Z	2.60
G	0.15
X	1.80
X1	0.60
Y	0.28
C	0.45

DF-S / MiniDIP



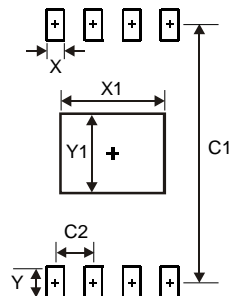
Dimensions	DF-S	MiniDIP
Z	10.26	6.91
X	1.2	0.60
Y	1.52	0.76
C	5.2	2.67

MSOP-8L



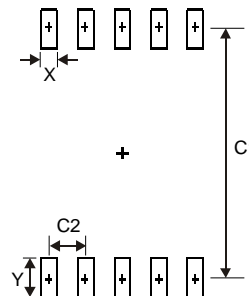
Dimensions	Value (in mm)
X	0.45
Y	1.4
C1	4.4
C2	0.65

MSOP-8L-EP



Dimensions	Value (in mm)
C1	4.2
C2	0.65
X	0.32
X1	1.95
Y	0.8
Y1	1.65

MSOP-10L

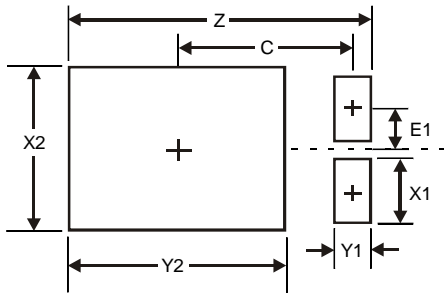


Dimensions	Value (in mm)
X	0.30
Y	1.4
C1	4.4
C2	0.50

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

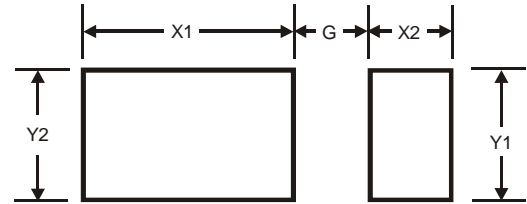
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

PowerDI[®]5



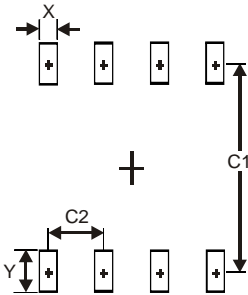
Dimensions	Value (in mm)
Z	6.6
X1	1.4
X2	3.6
Y1	0.8
Y2	4.7
C	3.87
E1	0.9

PowerDI[®]123 / PowerDI[®]323



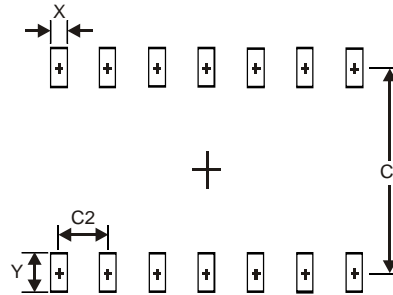
Dimensions	PowerDI [®] 123	PowerDI [®] 323
G	1.0	0.5
X1	2.2	2.0
X2	0.9	0.8
Y1	1.4	0.8
Y2	1.4	1.1

SOP-8L



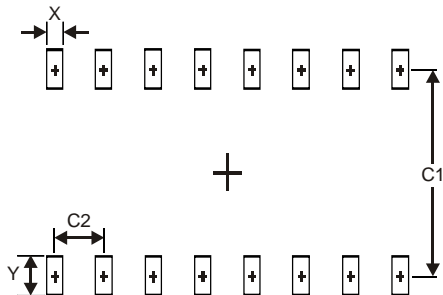
Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

SOP-14L



Dimensions	Value (in mm)
X	0.60
Y	1.50
C1	5.4
C2	1.27

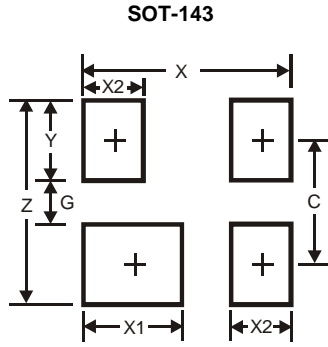
SOP-16L



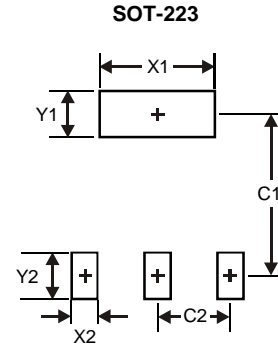
Dimensions	Value (in mm)
X	0.60
Y	1.50
C1	5.4
C2	1.27

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

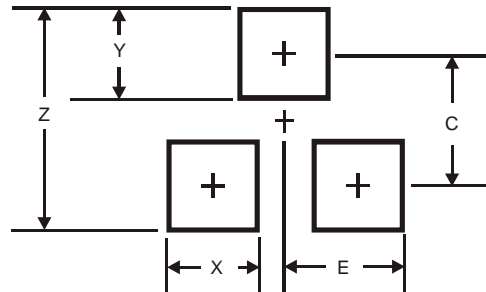


Dimensions	Value (in mm)
Z	2.70
G	1.30
X	2.50
X1	1.0
X2	0.60
Y	0.70
C	2.0



Dimensions	Value (in mm)
X1	3.3
X2	1.2
Y1	1.6
Y2	1.6
C1	6.4
C2	2.3

SOT-523 / SOT-323 / SOT-23 / SC-59

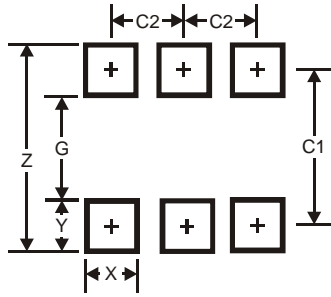


Dimensions	SOT-523	SOT-323	SOT-23	SC-59
Z	1.8	2.8	2.9	3.4
X	0.4	0.7	0.8	0.8
Y	0.51	0.9	0.9	1.0
C	1.3	1.9	2.0	2.4
E	0.7	1.0	1.35	1.35

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

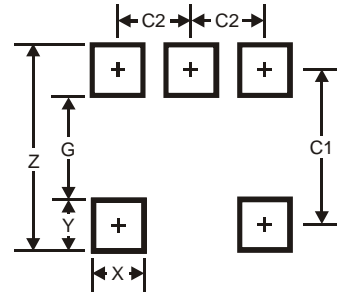
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

SC-74R / SOT-26 / SOT-363 / SOT-563



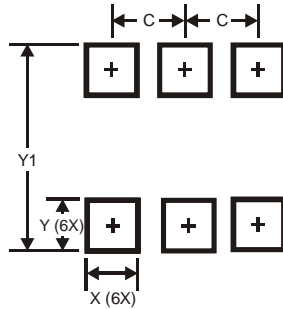
Dimensions	SC-74R / SOT-26	SOT-363	SOT-563
Z	3.20	2.5	2.2
G	1.60	1.3	1.2
X	0.55	0.42	0.375
Y	0.80	0.6	0.5
C1	2.40	1.9	1.7
C2	0.95	0.65	0.5

SOT-25 / SOT-353



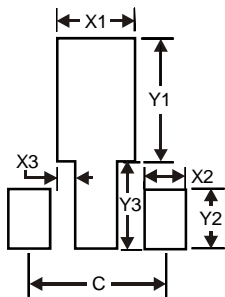
Dimensions	SOT-25	SOT-353
Z	3.20	2.5
G	1.60	1.3
X	0.55	0.42
Y	0.80	0.6
C1	2.40	1.9
C2	0.95	0.65

SOT-963



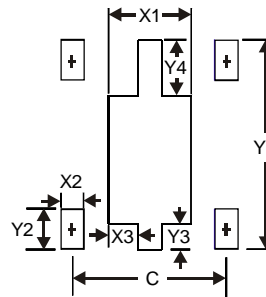
Dimensions	Value (in mm)
C	0.350
X	0.200
Y	0.200
Y1	1.100

SOT89-3L



Dimensions	Value (in mm)
X1	1.7
X2	0.9
X3	0.4
Y1	2.7
Y2	1.3
Y3	1.9
C	3.0

SOT89-5L

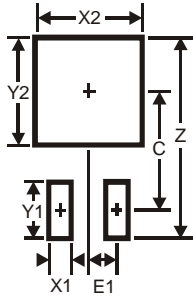


Dimensions	Value (in mm)
X1	1.7
X2	0.55
X3	0.4
Y1	4.6
Y2	1.2
Y3	0.5
Y4	1.1
C	3.0

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

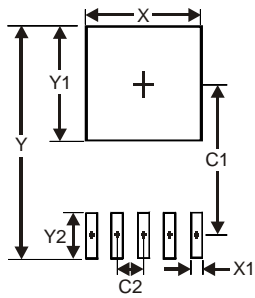
Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

TO252-3L (DPAK) / TO263-3L (D²PAK)



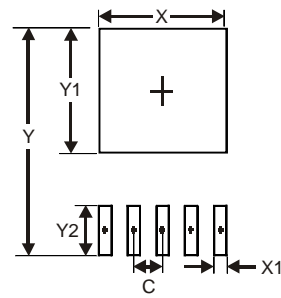
Dimensions	TO252-3L / DPAK	TO263-3L / D ² PAK
Z	11.6	16.9
X1	1.5	1.1
X2	7.0	10.8
Y1	2.5	3.5
Y2	7.0	11.4
C	6.9	9.5
E1	2.3	2.5

TO252-5L



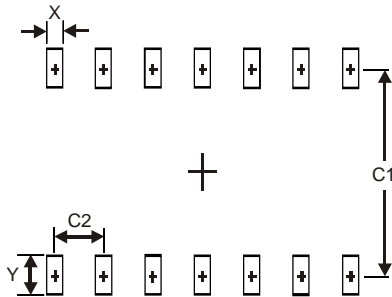
Dimensions	Value (in mm)
X	5.6
X1	0.6
Y	11.0
Y1	5.6
Y2	2.0
C1	7.2
C2	1.27

TO263-5L



Dimensions	Value (in mm)
X	10.9
X1	1.05
Y	15.7
Y1	9.1
Y2	2.5
C	1.7

TSSOP-14L



Dimensions	Value (in mm)
X	0.45
Y	1.45
C1	5.9
C2	0.65

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